

Abstract of Disclosure

The invention provides a semiconductor device and a method for manufacturing the same, enabling the semiconductor device to be high-densely packaged without lowering the final manufacturing yield of products.

A semiconductor device 100 includes the first semiconductor device 110 having a plurality of bumps 3 which are formed on the backside surface thereof, and the second semiconductor device 120 having a plurality of terminals 2 which are formed on the front surface thereof and are to be electrically connected with the bumps, the second semiconductor device being mounted on an area which is located on the backside surface of the first semiconductor device 110 without having any bump formed therein. The height of the second semiconductor device measured from the backside surface of the first semiconductor device is made lower than the height of the bump. The second semiconductor device is mounted on the first semiconductor device such that the surface provided with no terminal of the second semiconductor device is joined to the backside surface of the first semiconductor device with the help of an adhesive 115.